

L Number	Hits	Search Text	DB	Time stamp
2	8	"smart card" and IC and pad and chip and substrate and 29/\$.ccis.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT	2003/01/27 10:57
3	12	("4459607" "4460825" "4514785" "4549247" "4746392" "4829666" "4835846" "4850105" "4889980" "4996411" "5057460" "5057679").PN.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT	2003/01/27 10:54
5	0	"contactless smart card" and "contact protrusion"	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/27 10:59
6	3	"contactless smart card" and 29/\$.ccis.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/27 10:59
4	243	"contactless smart card"	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/27 10:59
1	134	"smart card" and IC and pad and chip and substrate	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/27 11:11
7	37	("4498122" "4628406" "4874721" "5073840" "5147210" "5399903" "5430441" "5450290" "5463404" "5473118" "5514475" "5574470" "5598032" "5637920" "5677246" "5740606" "5751256" "5847931" "5880934" "5892661" "5906042" "5909050" "5915753" "5926696" "5989936" "5994168" "6016598" "6020220" "6022761" "6060150" "6084781" "6107679" "6107689" "6111323" "6127025" "6136733" "6141210").PN.	USPAT	2003/01/27 11:08
8	21	"smart card" and IC and pad and chip and substrate and 257/\$.ccis.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/27 11:12

US-PAT-NO: 6492717

DOCUMENT-IDENTIFIER: US 6492717 B1

TITLE: Smart card module and method of assembling the same

DATE-ISSUED: December 10, 2002

INVENTOR-INFORMATION:

NAME	CITY	STATE	ZIP
CODE COUNTRY			
Gore; Kiron P.	Libertyville	IL	N/A
N/A			
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N/A			

US-CL-CURRENT: 257/679; 257/678 ; 257/784 ; 257/787 ;
361/736 ; 361/737

ABSTRACT:

A module (10) for use with a smart card (50) is disclosed. The module (10) includes a substrate (14) having a first side (16) and a second side (18). The first and second sides each have deposited thereon a metallic layer (19, 21), with the substrate (14) having a thickness of about 125 microns. A die (22) is mounted adjacent the substrate first side (16), with the die (22) being coupled to the substrate first side (16) by a plurality of wire leads (24). A protective coating (26) covers the die (22), with the module having a total thickness of about 525 microns.

32 Claims, 4 Drawing figures

Exemplary Claim Number: 1

Number of Drawing Sheets: 3

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Document Listing

Document	Image pages	Text pages	Error pages
US 5528222 A	15	1	0
Total	15	1	0

US-PAT-NO: 5528222

DOCUMENT-IDENTIFIER: US 5528222 A

TITLE: Radio frequency circuit and memory in thin flexible package

DATE-ISSUED: June 18, 1996

INVENTOR-INFORMATION:

NAME	CITY	STATE	ZIP
CODE COUNTRY			
Moskowitz; Paul A. N/A	Yorktown Heights	NY	N/A
Brady; Michael J. N/A	Brewster	NY	N/A
Coteus; Paul W. N/A	Yorktown Heights	NY	N/A

US-CL-CURRENT: 340/572.7; 29/825 ; 29/829 ; 29/836 ;
340/10.1 ; 340/5.6

ABSTRACT:

A novel thin and flexible radio frequency (RF) tag has a semiconductor circuit with logic, memory, and a radio frequency circuits, connected to an antenna with all interconnections placed on a single plane of wiring without crossovers. The elements of the package (substrate, antenna, and laminated covers) are flexible. The elements of the package are all thin. The tag is thin and flexible, enabling a unique range of applications including: RF ID tagging of credit cards, passports, admission tickets, and postage stamps.

29 Claims, 19 Drawing figures

Exemplary Claim Number: 1

Number of Drawing Sheets: 10